



## SSC8126GN1

N-Channel Enhancement Mode MOSFET with ESD protection

### ➤ Features

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$	$I_D$	ESD
20V	$\pm 8V$	210m $\Omega$ @4V5	1A	2K
		260m $\Omega$ @2V5		
		330m $\Omega$ @1V8		

### ➤ Description

This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

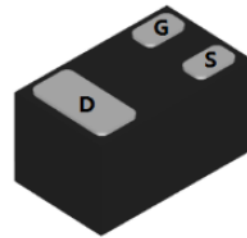
### ➤ Applications

- Load Switch
- Portable Devices

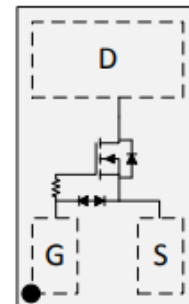
### ➤ Ordering Information

Device	Package	Shipping
SSC8126GN1	DFN1006-3L	10000/Reel

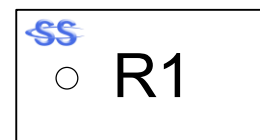
### ➤ Pin configuration



DFN1006-3L (Bottom View)



Pin Configuration (Top View)



Marking

**➤ Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	20	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 8$	V
Continuous Drain Current <sup>a</sup>	$I_D$	1	A
Pulsed Drain Current <sup>b</sup>	$I_{DM}$	3	A
Power Dissipation <sup>c</sup>	$P_D$	0.32	W
Power Dissipation <sup>a</sup>	$P_{DSM}$	0.18	W
Operation junction temperature, Storage temperature range	$T_J, T_{STG}$	-55 to 150	$^{\circ}\text{C}$

**➤ Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	690	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	379	

Note:

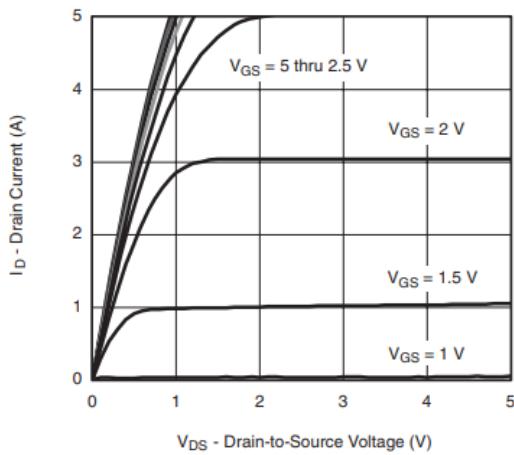
- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

**➤ Electrical Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

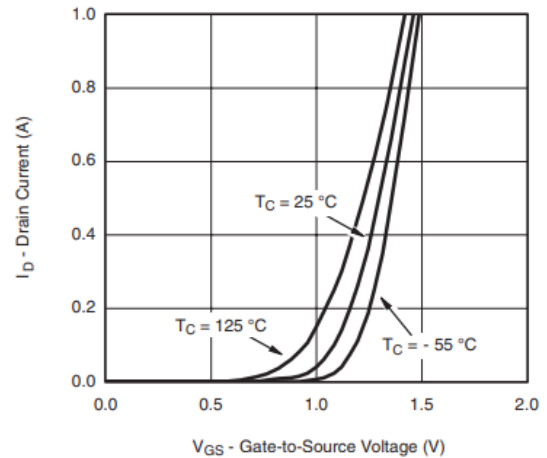
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.68	1	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{V}, I_D = 0.5\text{A}$		210	350	m $\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 0.35\text{A}$		260	420	
		$V_{GS} = 1.8\text{V}, I_D = 0.35\text{A}$		330	500	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-Source Leak Current	$I_{GSS}$	$V_{GS} = \pm 8\text{V}, V_{DS} = 0\text{V}$			$\pm 10$	$\mu\text{A}$
Transconductance	$G_{FS}$	$V_{DS} = 5\text{V}, I_D = 0.5\text{A}$		2		s
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = 0.5\text{A}$		0.7	1.3	V
Input Capacitance	$C_{ISS}$	$V_{DS} = 10\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$		66		pF
Output Capacitance	$C_{OSS}$			18		
Reverse Transfer Capacitance	$C_{RSS}$			9		
Turn-on Delay Time	$T_{D(ON)}$	$V_{GS} = 4.5\text{V}, V_{DS} = 10\text{V},$ $R_G = 6\Omega, I_D = 0.6\text{A}$		20		ns
Rise Time	$T_r$			13		
Turn-off Delay Time	$T_{D(OFF)}$			40		
Fall Time	$T_f$			12		



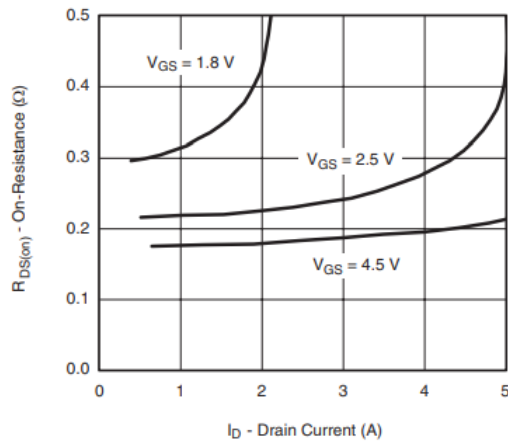
➤ **Typical Performance Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**



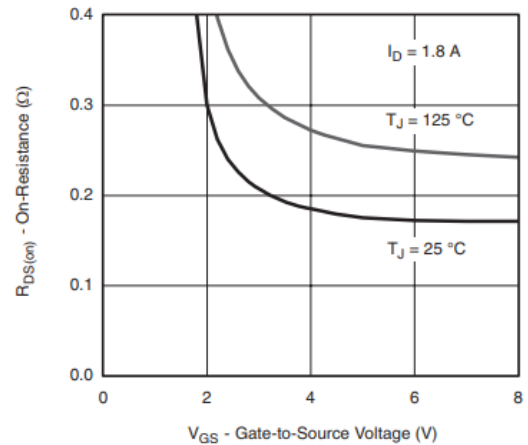
**Output Characteristics**



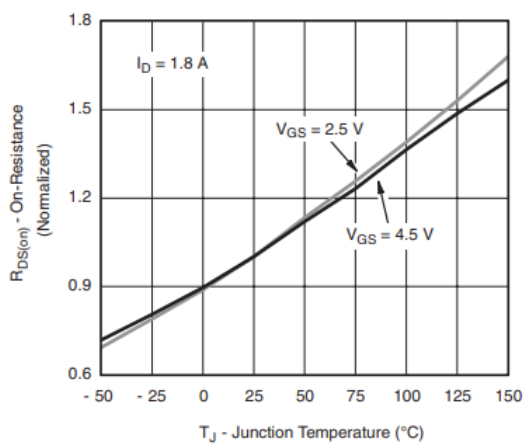
**Transfer Characteristics**



**On-Resistance vs. Drain Current and Gate Voltage**



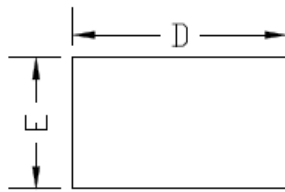
**On-Resistance vs. Gate-to-Source Voltage**



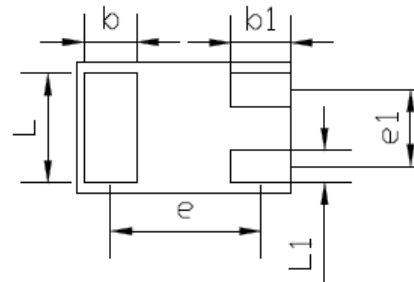
**On-Resistance vs. Junction Temperature**

## ➤ Package Information

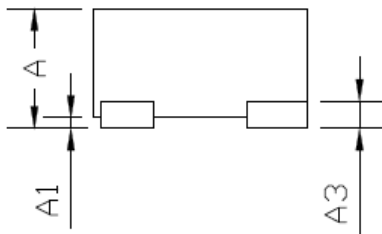
### POD



TOP VIEW



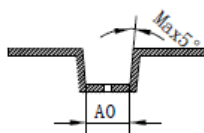
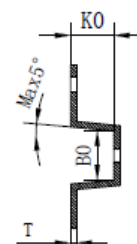
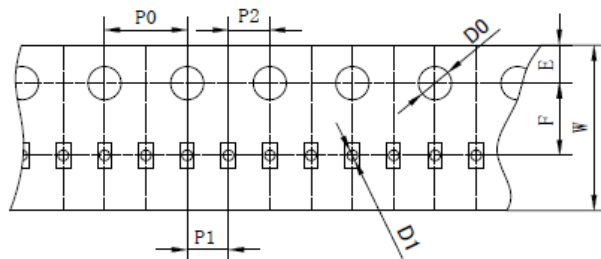
BOTTOM VIEW



SIDE VIEW

COMMON DIMENSION (MM)			
PKG	DFN1006		
REF.	MIN.	NOM.	MAX
A	>0.4	—	0.50
A1	0.00	—	0.05
A3	0.125REF.		
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b	0.20	0.25	0.30
b1	0.20	0.30	0.40
L	0.45	0.50	0.55
L1	0.10	0.15	0.20
e	0.675		
e1	0.35		

### Tape Data

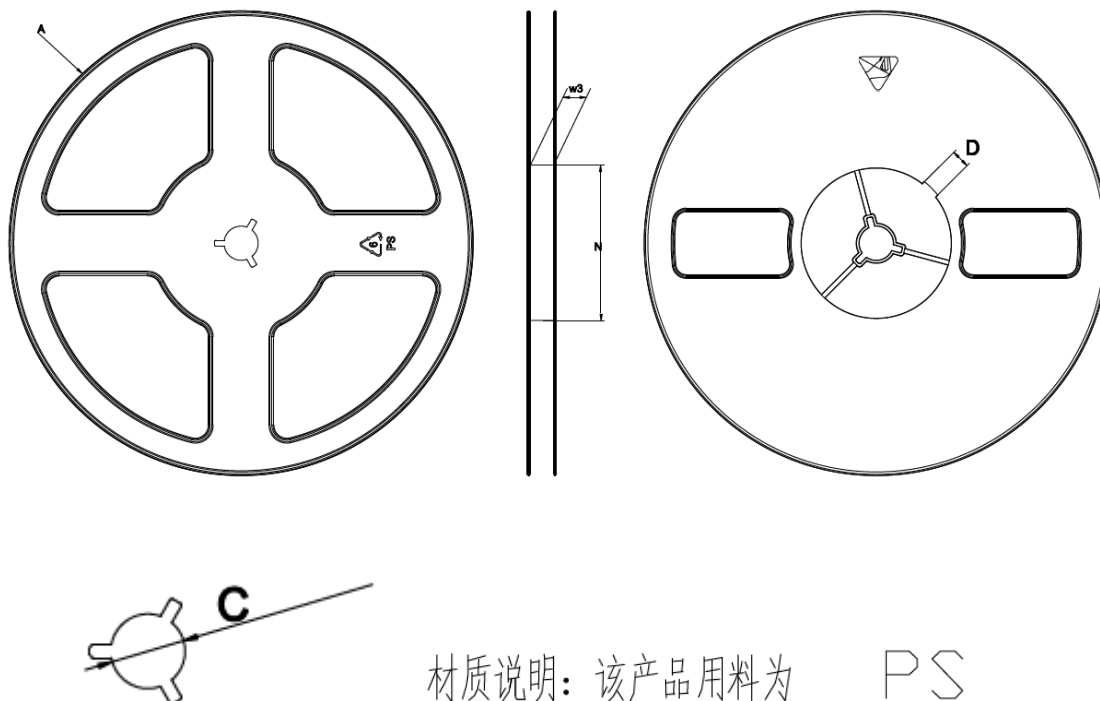


#### NOTE:

1. 材料：黑色防静电材料；
2. 10个链孔的累积公差不能超过  $\pm 0.2$
3. 尺寸符合EIA-481-E的要求。

SYMBOL	A0	B0	K0	P0	P1	P2
SPEC	$0.69 \pm 0.05$	$1.15 \pm 0.05$	$0.60 \pm 0.05$	$4.00 \pm 0.10$	$2.00 \pm 0.05$	$2.00 \pm 0.05$
SYMBOL	T	E	F	D0	D1	W
SPEC	$0.18 \pm 0.03$	$1.75 \pm 0.10$	$3.50 \pm 0.05$	$1.55 \pm 0.05$	$0.50 \pm 0.05$	$8.00^{+0.5}_{-0.1}$

## Reel Data



材质说明：该产品用料为

PS

TYPE	A	N	C	D	w3
8MM	$\begin{matrix} +1 \\ \text{Ø178} \\ -1 \end{matrix}$	$\begin{matrix} +1 \\ \text{Ø60} \\ -1 \end{matrix}$	$\begin{matrix} +0,3 \\ \text{Ø13,3} \\ -0,3 \end{matrix}$	$7,5 \pm 0,5$	$9 \pm 0,3$



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